

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]



PROJECT TITLE: 27U...29Uin to 24U@11A Synch. Buck with OVP	
DESIGNED FOR: Public Release	
FILE NAME: PMP30189 Rev_B PCB.PcbDoc	
ENGINEER: R. Scibilia	LAYOUT BY: R. Scibilia
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

BOARD #: PMP30189		REV: B	SUN REV: Not In VersionControl	Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.	
TID #:		GENERATED : 6/26/2017 12:39:35 PM		TEXAS INSTRUMENTS	
PLOT NAME = Assembly Layer Top					

1

2

3

4

5

6

A

A

B

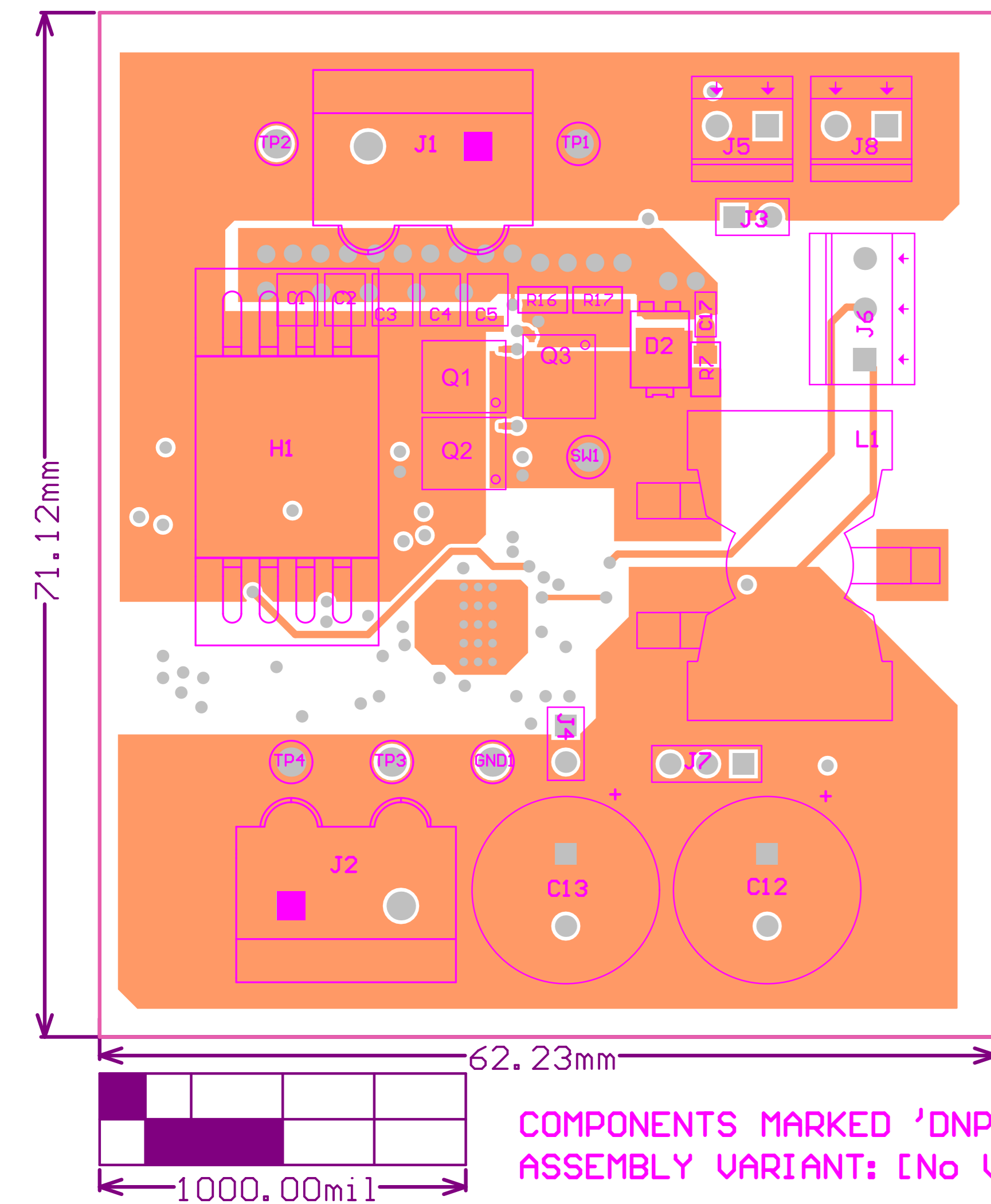
B

C

C

D

D



PROJECT TITLE: 27U...29Uin to 24U@11A Synch. Buck with OVP	
DESIGNED FOR: Public Release	
FILE NAME: PMP30189 Rev_B PCB.PcbDoc	
ENGINEER: R. Scibilia	LAYOUT BY: R. Scibilia
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TID #:			ENGINEER: R. Scibilia		
PLOT NAME = Copper Top	GENERATED : 6/26/2017 12:39:36 PM	TEXAS INSTRUMENTS		SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

1

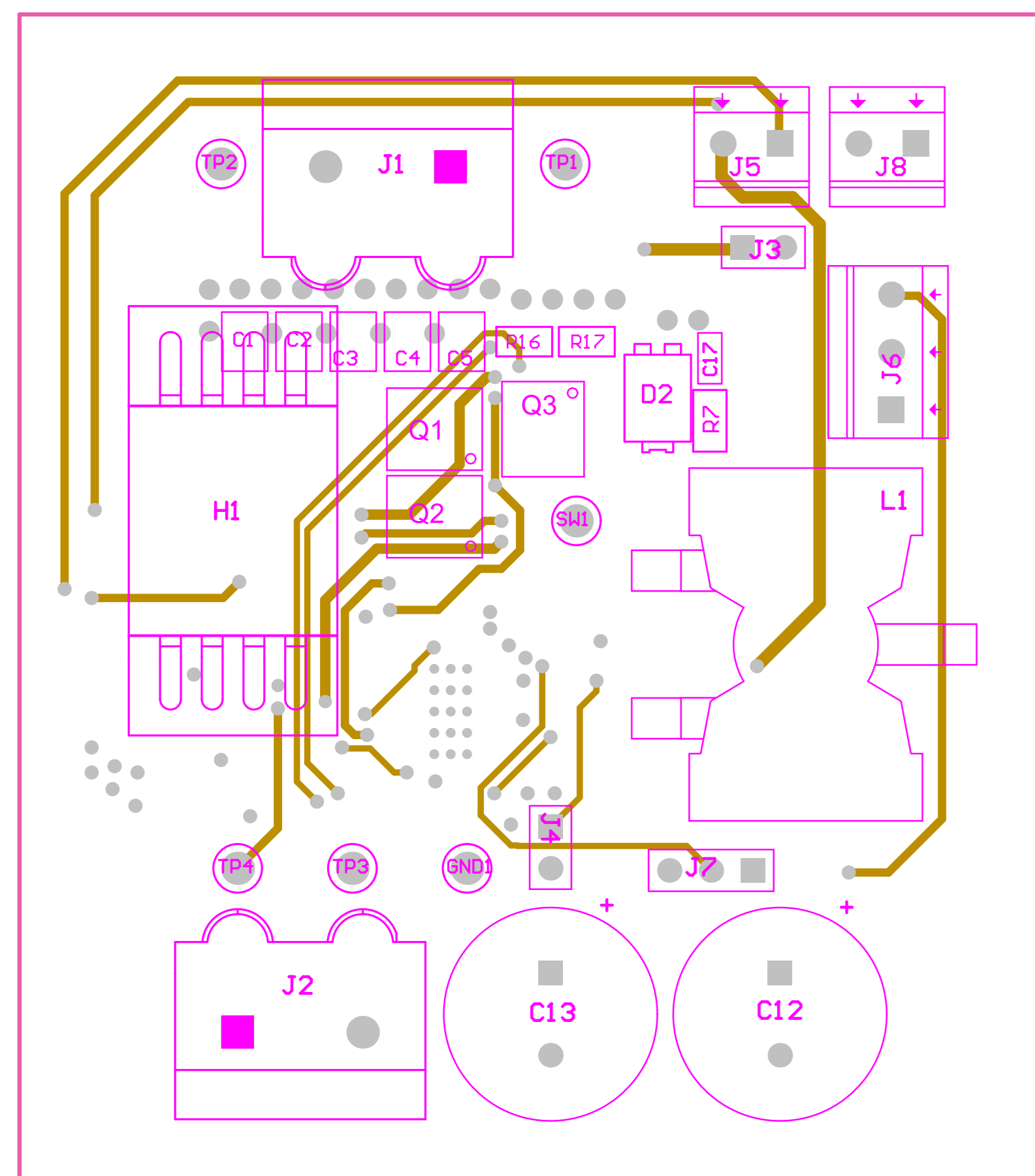
2

3

4

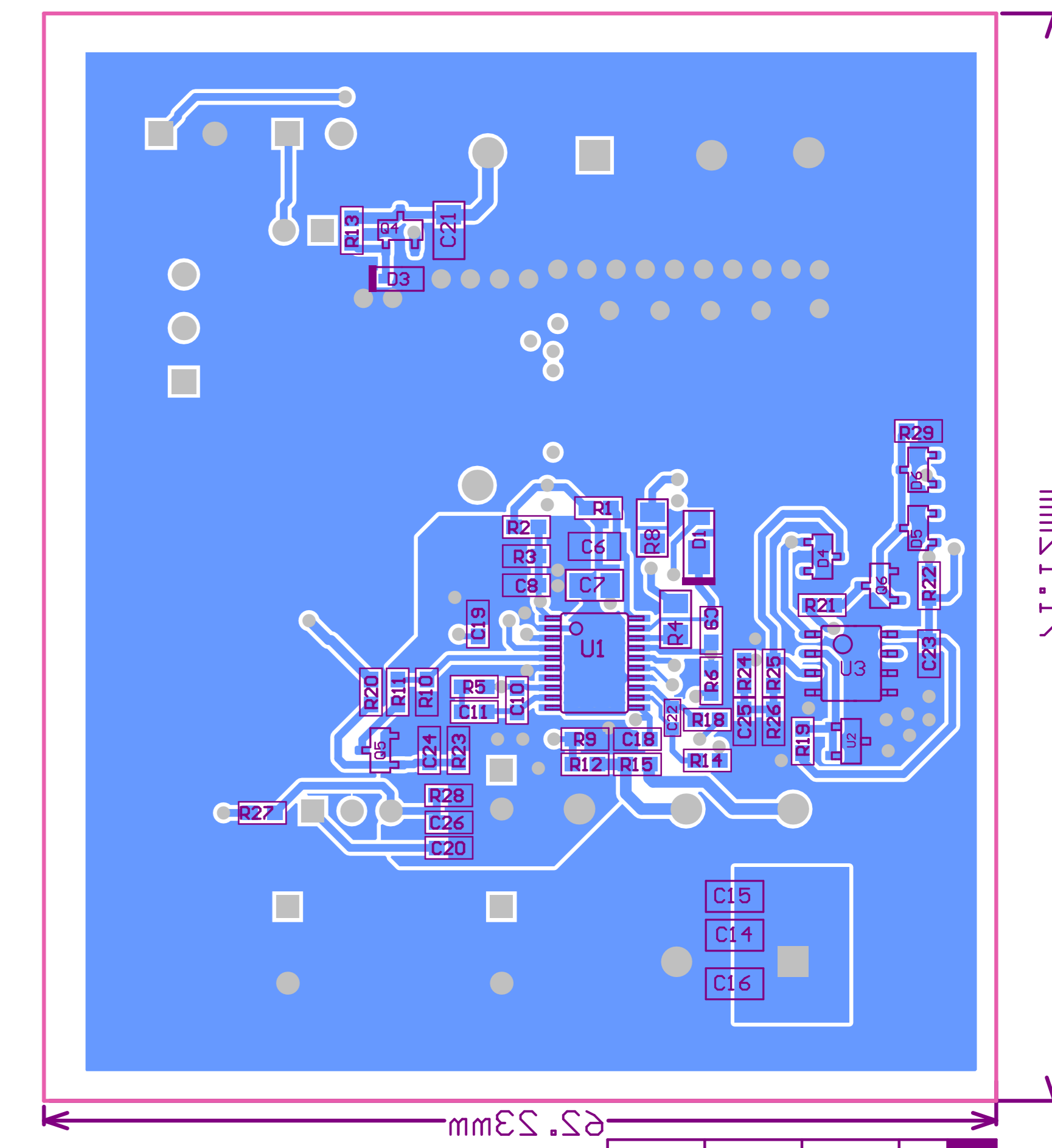
5

6




COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

	BOARD #: PMP30189	REV: B	SUN REV: Not In VersionControl
	TID #:		
PLOT NAME = Inner Layer 1	GENERATED : 6/26/2017 12:39:36 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

	
PROJECT TITLE: ZVU...Zavin to Z4UG1A Synch. Buck with OVP	
DESIGNED FOR: Public Release	
FILE NAME: PMP30189 Rev_B_PCB.PcbDoc	
LAYOUT BY: R. Scidilia	ENGINEER: R. Scidilia
ALTIM DESIGNER VERSION: 16.0.9.368	SCALE: 1.00

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PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30189	REV: B	
	TID #:		
PLOT NAME = Copper Bottom	GENERATED : 6/26/2017 12:39:37 PM	TEXAS INSTRUMENTS	

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